

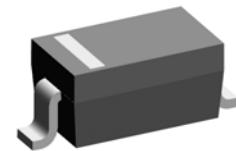
Small Signal Zener Diode

General Description

These diodes small signal Zener diodes, fabricated in planar technology. Miniature surface mount package is excellent for hand-held and portable applications where space is limited.

Features and Benefits

- Silicon epitaxial planar diode
- Low Zener impedance and low leakage current
- Standard Zener voltage tolerance is 4.3%.
- Full lead (Pb)-free device and RoHS compliant device
- Available in "Green" device



SOD-323



RoHS



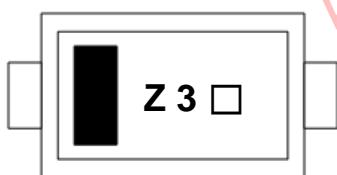
Applications

- Voltage regulator

Ordering Information

Part Number	Marking Code	Package	Packaging
SDZ5V6D	Z3 □	SOD-323	Tape & Reel

Marking Information

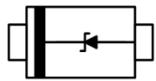


Z 3 = Specific Device Code

□ = Year & Week Code Marking

■ = Color band denote cathode

Pinning Information

Pin	Description	Simplified Outline	Graphic Symbol
1	Cathode		
2	Anode		

SDZ5V6D

Absolute Maximum Ratings ($T_{amb}=25^{\circ}C$, Unless otherwise specified)

Characteristic	Symbol	Ratings	Unit
Power dissipation ¹⁾	P_D	120	mW
Maximum operating junction temperature	T_J	150	°C
Storage temperature range	T_{stg}	-55°C to +150°C	°C
Operating junction temperature range	T_{opr}	-55°C to +150°C	°C

¹⁾ Device mounted on FR-4 board with recommended pad layout.

Thermal Characteristics ($T_{amb}=25^{\circ}C$, Unless otherwise specified)

Characteristic	Symbol	Ratings	Unit
Thermal resistance, junction to ambient ¹⁾	$R_{th(j-a)}$	1040	°C/W

¹⁾ Device mounted on FR-4 board with recommended pad layout.

Electrical Characteristics ($T_{amb}=25^{\circ}C$, Unless otherwise specified)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Zener voltage	V_Z	$I_Z = 5mA$	5.35	5.6	5.85	V
Dynamic impedance	Z_{ZT}	$I_Z = 5mA$	-	-	25	Ω
KNEE dynamic impedance	Z_{ZK}	$I_Z = 0.25mA$	-	-	1800	Ω
Reverse leakage current	I_R	$V_R = 3V$	-	-	2	uA

Rating and Characteristic Curves

Fig. 1) Typical Zener Characteristics

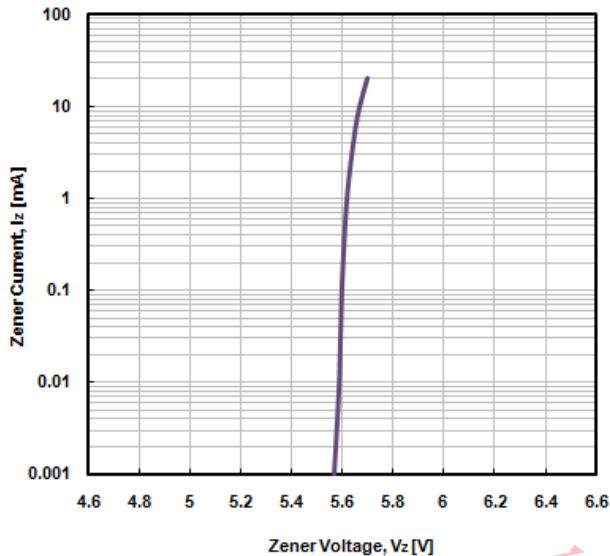


Fig. 2) Zener voltage vs. Ambient Temperature

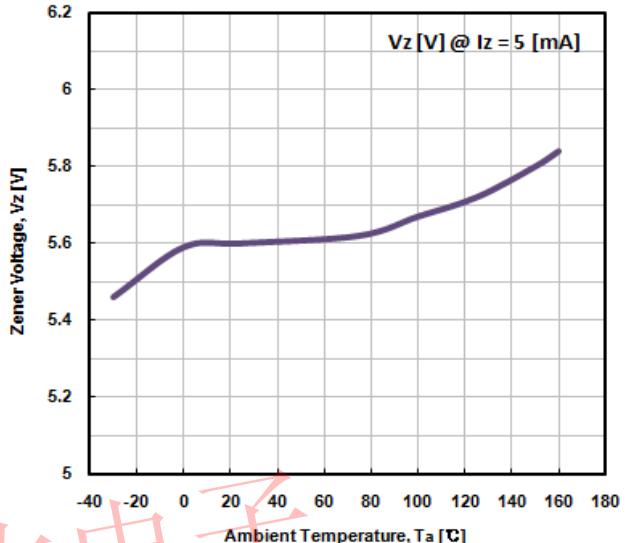


Fig. 3) Typical Capacitance Characteristics

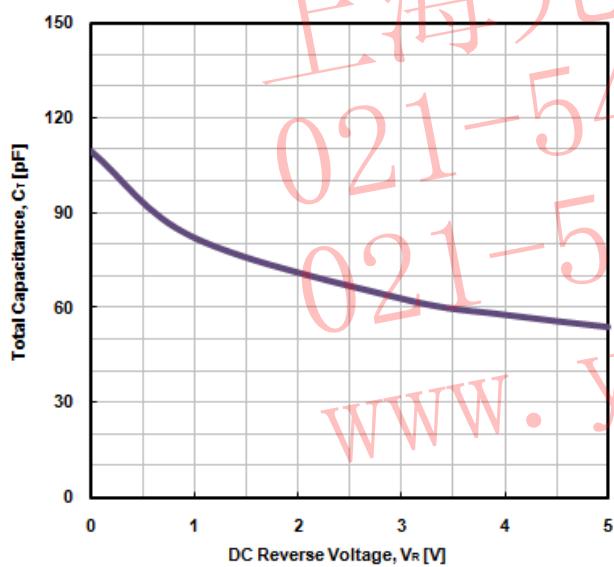
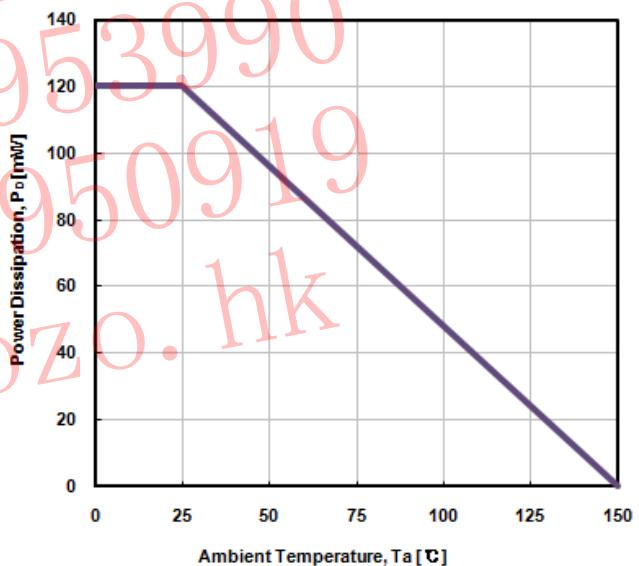
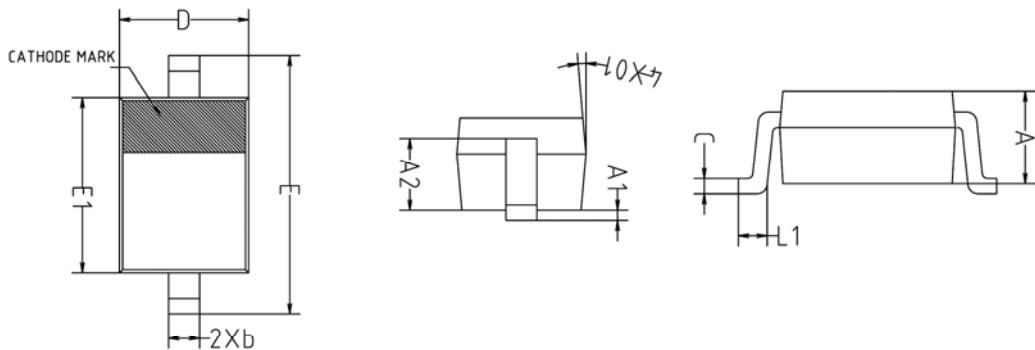


Fig. 4) Power Dissipation vs. Ambient Temperature



Package Outline Dimensions

SYMBOL	MILLIMETERS			NOTE
	MINIMUM	NOMINAL	MAXIMUM	
A	0.850	-	0.950	
A1	0.000	-	0.100	
A2	0.650	0.700	0.750	
b	0.250	0.300	0.350	
c	0.110	0.150	0.190	
D	1.200	1.250	1.300	
E	2.400	2.500	2.600	
E1	1.650	1.700	1.750	
L1	0.200	-	0.300	
θ2	5° REF			

※ Recommend PCB solder land (Unit : mm)

